AMENDMENTS TO THE CLAIMS

1.-50. (cancelled).

51. (New) An apparatus for electroplating a semiconductor product, comprising:

a reservoir configured to contain an electroplating solution;

a support associated with the reservoir and configured to hold a substrate such that when the reservoir is filled with solution and a substrate is held on the support, the substrate is in contact with solution contained in the reservoir; and

an electrode configured such that when the reservoir is filled with electroplating solution, the electrode also contacts the solution, and

wherein the distance between the electrode and the support is changeable between a first operating distance and a second operating distance such that when the reservoir is filled with solution, both the electrode and a substrate held on the support maintain contact with the solution through any change in distance between the first operating distance and the second operating distance.

52. (New) The apparatus according to claim 51, wherein the electrode is movable relative to the support to thereby change the distance between the electrode and the support.

53. (New) The apparatus according to claim 51, wherein the support is movable relative to the electrode to thereby change the distance between the electrode and the support.

54. (New) The apparatus according to claim 51, wherein the support includes conductive contacts for holding a substrate thereto.

55. (New) The apparatus according to claim 51, wherein the reservoir is formed as a cascade-type structure.

56. (New) The apparatus according to claim 51, further comprising a device for agitating solution contained in the reservoir.

57. (New) The apparatus according to claim 56, wherein the device for agitating comprises a diffuser.

58. (New) The apparatus according to claim 56, wherein the device for agitating comprises a baffle plate.

59. (New) An apparatus for electroplating a semiconductor product, comprising:

a reservoir configured to contain an electroplating solution;

a plurality of supports associated with the reservoir, each support configured to hold a substrate such that when the reservoir is filled with solution and a substrate is held on the support, the substrate is in contact with solution contained in the reservoir; and

at least one electrode configured such that when the reservoir is filled with electroplating solution, each of the at least one electrode also contacts the solution, and wherein the distance between the at least one electrode and the plurality of supports is changeable between a first operating distance and a second operating distance such that when the reservoir is filled with solution and at least one of the plurality of

supports has a respective substrate held therein, each of the at least one electrode and each substrate maintain contact with the solution through any change in distance between the first operating distance and the second operating distance.

60. (New) The apparatus according to claim 59, wherein

the at least one electrode is a plurality of electrodes corresponding in number with the number of supports in the plurality of supports,

each electrode is paired with a corresponding one of the plurality of supports, and

the distance between each electrode and corresponding support is changeable between the first operating distance and the second operating distance.

61. (New) The apparatus according to claim 59, wherein each of the at least one electrode is movable relative to the plurality of supports to thereby change the distance between the first operating distance and the second operating distance.

62. (New) The apparatus according to claim 59, wherein each of the plurality of supports is movable relative to the at least one electrode to thereby change the distance between the first operating distance and the second operating distance.

63. (New) The apparatus according to claim 59, wherein each of the plurality of supports includes conductive contacts for holding a substrate thereto.

64. (New) The apparatus according to claim 59, wherein the reservoir is formed as a cascade-type structure.

65. (New) The apparatus according to claim 59, further comprising a device for agitating solution contained in the reservoir.

66. (New) An apparatus for electroplating a semiconductor product, comprising:

a reservoir configured to contain an electroplating solution;

a support associated with the reservoir and configured to hold a substrate such that when the reservoir is filled with solution and a substrate is held on the support, the substrate is in contact with solution contained in the reservoir; and

an first electrode located at a position which is a first distance away from the support and which corresponds to an initial electroplating position, wherein when the reservoir is filled with electroplating solution, the first electrode also contacts the solution, and

a second electrode located at a position which is a second distance away from the support and which corresponds to a high efficiency electroplating position, wherein when the reservoir is filled with electroplating solution, the second electrode also contacts the solution.

67. (New) The apparatus according to claim 66, wherein the support includes conductive contacts for holding a substrate thereto.

68. (New) The apparatus according to claim 66, wherein the reservoir is formed as a cascade-type structure.

69. (New) The apparatus according to claim 66, further comprising a device for agitating solution contained in the reservoir.